IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of	:	
	:	
Alexander T. SCHWARM	:	
	:	
Serial No. 10/765,921	:	Group Art Unit:
	:	
Filed: January 29, 2004	:	Examiner:

For: SYSTEM, METHOD, AND MEDIUM FOR MONITORING PERFORMANCE OF AN ADVANCED PROCESS CONTROL SYSTEM

INFORMATION DISCLOSURE STATEMENT

Honorable Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In accordance with the provisions of 37 C.F.R. 1.56, 1.97 and 1.98, the attention of the Patent and Trademark Office is hereby directed to the documents listed on the attached form PTO-1449. It is respectfully requested that the documents be expressly considered during the prosecution of this application, and that the documents be made of record therein and appear among the "References Cited" on any patent to issue therefrom. Copies of any cited U.S. Patents and U.S. Patent Publications are not being submitted in accordance with 37 CFR 1.98(a)(2)(i).

This Information Disclosure Statement is being filed within three months of the U.S. filing date OR before the mailing date of a first Office Action on the merits. No certification or fee is required.

In accordance with 37 C.F.R. § 1.97(g) and (h), the filing of this IDS should not be construed as a representation that a search had been made or that information cited is, or is considered to be, material to patentability as defined in 37 C.F.R.§ 1.56 (b), or that any cited document listed or attached is (or constitutes) prior art. Unless otherwise indicated, the date of

publication indicated for an item is taken from the face of the item, and Applicant reserves the right to prove that the date of publication is in fact different.

The references listed on Sheet 1 of the attached PTO-1449 Forms were cited in a patentability investigation and/or a corresponding foreign or PCT application relating to the above-referenced application. The remaining references are from potentially related patent applications, and possibly other sources.

No fee is believed to be required; however, the Commissioner is authorized to charge any deficiency in any fees pursuant to 37 CFR § 1.17 associated with this communication and to credit any excess payment to Deposit Account No. 08-0219.

Respectfully submitted,

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INFORMATION DISCLOSURE CITATION IN AN APPLICATION (PTO-1449)

ATTY. DOCKET NO.	SERIAL NO.
007733 USA/FPS/MMCS/APC	10/765,921
APPLICANT: Alexander T. SCHWARM	
FILING DATE: January 29, 2004	GROUP

U.S. PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
	5,642,296	06/24/97	Saxena			07/29/93
	5,646,870	07/08/97	Krivokapic et al.			02/13/95
	5,719,796	02/17/98	Chen			12/04/95
	5,787,269	07/28/98	Hyodo			09/19/95
	5,859,964	01/12/99	Wang et al.			10/25/96
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	WO 01/25865 A1	04/12/01	WO			X	

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

	Chang, Norman H. and Costas J. Spanos. February 1991. "Continuous Equipment Diagnosis Using Evidence Integration: An LPCVD Application." *IEEE Transactions on Semiconductor Manufacturing*, v. 4, n. 1, pp. 43-51.
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	"Semiconductor Manufacturing: An Overview." <http://users.ece.gatech.edu/~gmay/overview.html>

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	3,229,198	01/11/66	Libby			09/28/62
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	5,912,678	06/15/99	Saxena et al.			04/14/97
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	FILING DATE January 29, 2004	GROUP

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